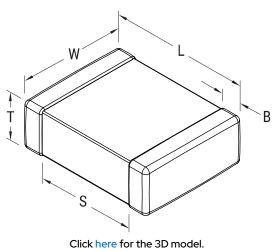


C0603X109BATAC7411

General Information

SMD Comm X8G HT150C Flex, Ceramic, 1 pF, +/-0.1 pF, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm





	Series	SMD Comm X8G HT150C Flex
	Style	SMD Chip
	Description	SMD, MLCC, High Temperature, Ultra-Stable
	Features	High Temperature, Ultra-Stable
	RoHS	Yes
	Termination	Flexible Termination
	Marking	No
	AEC-Q200	No
	Typical Component Weight	4.6 mg
	Shelf Life	78 Weeks
	MSL	1

Dimensions				
Chip Size	0603			
L	1.6mm +/-0.17mm			
W	0.8mm +/-0.15mm			
Т	0.8mm +/-0.15mm			
S	0.4mm MIN			
В	0.45mm +/-0.15mm			

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

Specifications			
Capacitance	1pF		
Measurement Condition	1 MHz 1.0Vrms		
Tolerance	+/-0.1 pF		
Voltage DC	250 VDC		
Dielectric Withstanding Voltage	625 VDC		
Temperature Range	-55/+150°C		
Temp. Coefficient	X8G		
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms		
Dissipation Factor	0.1% 1 MHz 1.0Vrms		
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours		
Insulation Resistance	100 GOhms		

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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